| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L1 | 2 | shadow adj mask with chamfered | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/26 23:19 |
| L2 | 9 | etch$3 with (wire rod screen shadow stencil) near mask$3 and chamfered | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/26 23:31 |
| L3 | 0 | etch$3 with (wire rod screen shadow stencil) near mask$3 and beveled near opening | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/26 23:31 |
| L4 | 0 | etch$3 with (wire rod screen shadow stencil) near mask$3 and beveled with opening | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/26 23:31 |
| L5 | 6 | etch$3 with (wire rod screen shadow stencil) near mask$3 and beveled | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/26 23:31 |
| S1 | 398 | (216/12).CCLS. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/26 23:18 |
| S2 | 170 | (roughen$3 texturiz$3) with (surface substrate wafer workpiece) and (RF adj electrode plasma RIE) and (shadow adj mask plate near (hole aperture opening)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/22 16:14 |
| S3 | 0 | S1 and S2 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/22 14:57 |
| S4 | 41 | (roughen$3 texturiz$3) with (surface substrate wafer workpiece) and (RF adj electrode plasma RIE etch$3 ) and (wire rod screen) near mask | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/22 16:40 |

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|---|---|---|---|---|---|---|
| S5 | 50 | (roughen$3 texturiz$3) with (surface substrate wafer workpiece) and (RF adj electrode plasma RIE etch$3 ) and (stencil) near mask | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/22 16:40 |
| S6 | 50 | (roughen$3 texturiz$3) with (surface substrate wafer workpiece) and (plasma RIE etch$3) and (stencil) near mask | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/22 16:41 |
| S7 | 2643 | etch$3 with (wire rod screen shadow stencil) near mask$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/26 23:21 |
| S8 | 1290 | etch$3 with (wire rod screen shadow stencil) near mask$3 | EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/23 15:48 |
| S9 | 1353 | etch$3 with (wire rod screen shadow stencil) near mask$3 | US-PGPUB; USPAT | OR | OFF | 2005/06/23 15:48 |
| S10 | 1155 | etch$3 with (wire rod screen shadow stencil) adj mask$3 | US-PGPUB; USPAT | OR | OFF | 2005/06/23 15:49 |
| S11 | 167 | etch$3 near (wire rod screen shadow stencil) adj mask$3 | US-PGPUB; USPAT | OR | OFF | 2005/06/23 15:49 |
| S12 | 36 | S11 and rough$5 | US-PGPUB; USPAT | OR | OFF | 2005/06/23 16:16 |
| S13 | 52 | etch$3 same (wire plate screen grid mask) with (promote encourage enhance) with (deposit$3 micromask micro-mask micro adj mask residue) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/23 16:45 |
| S14 | 7760 | hatakeyama.in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/23 17:41 |
| S15 | 523 | S14 and etch$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/23 17:41 |
| S16 | 131 | S15 and rough$5 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/23 17:41 |

| S17 | 105 | S16 and mask$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/23 17:42 |
|-----|-----|----------------|------------------------------------------|----|-----|------------------|
| S18 | 47 | S17 and (rie plasma) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/06/23 17:42 |